Silicon N-Channel Power MOS FET Module

HITACHI

Application

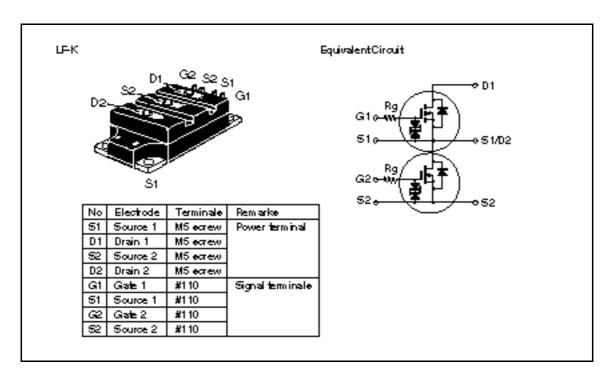
High Speed Power Switching

Features

- Equipped with Power MOS FET
- · Low on-resistance
- · High speed switching
- · Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- · Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$) (Per FET chip)

Item	Symbol	Rating	Unit ∨	
Drain source voltage	$V_{(BR)DSS}$	500		
Gate source voltage	$V_{(BR)GSS}$	±30	V	
Drain current	I _D	150	А	
Drain peak current	I D(peak)	360	А	
Body to drain diode reverse drain current	I _{DR}	150	А	
Body to drain diode reverse peak current	I _{DR(peak)}	360	А	
Channel dissipation	Pch*1	500	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-45 to +125	°C	
Insulation dielectric	Viso*2	2000	Vrms	

Notes: 1. Value at Ta = 25°C

2. Base to terminals AC minute

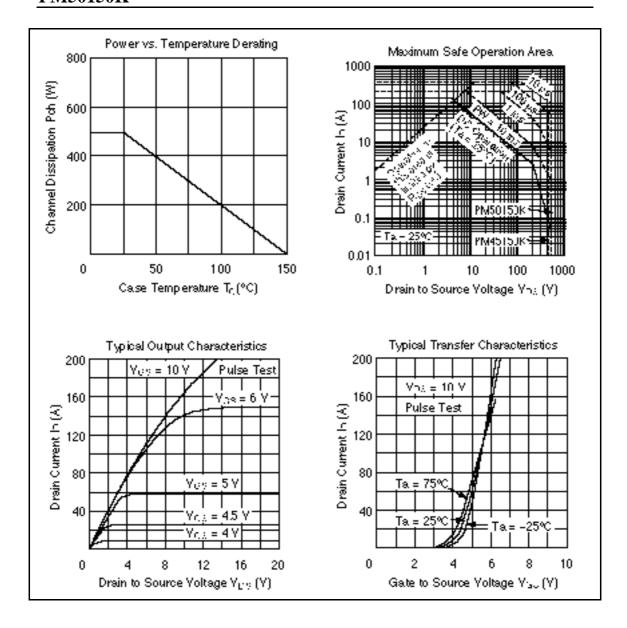
Electrical Characteristics (Ta = 25°C) (Per FET chip)

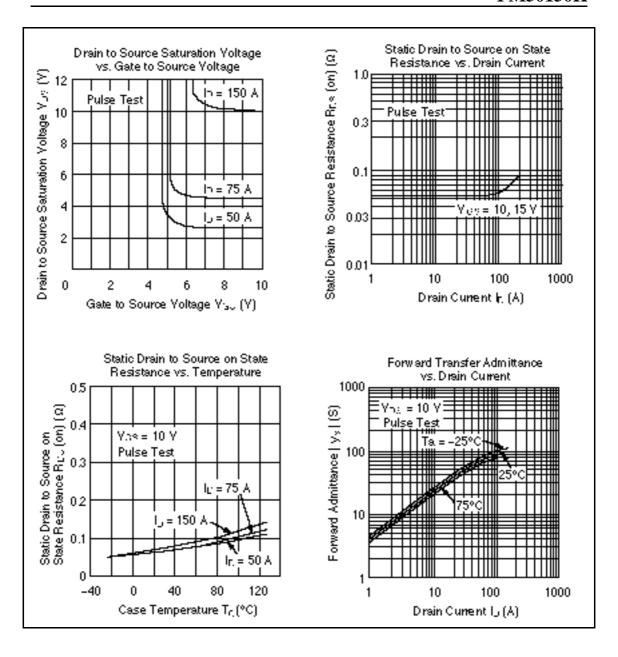
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	500	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0 \ V$
Drain leak current	I _{DSS}	_	_	1	mA	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Drain to source saturation voltage	$V_{\mathrm{DS(on)}}$	_	4.5	6.0	V	$I_D = 75 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Static drain to source on state resistance	$R_{\mathrm{DS(on)}}$	_	0.06	0.08		$I_D = 75 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	y _{fs}	_	80	_	S	$I_D = 75 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	22600	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}$
Output capacitance	Coss	_	4600	_	_	f = 1 MHz
Reverse transfer capacitance	Crss	_	580	_	_	
Turn-on delay time	t _{d(on)}	_	280	_	ns	$I_D = 75 \text{ A}, V_{GS} = 10 \text{ V}$
Rise time	t _r	_	820	_	<u> </u>	Rg = 50
Turn-off delay time	$t_{d(off)}$	_	1190	_		$R_{L} = 0.4$
Fall time	t _f	_	400	_		
Body to drain diode forward voltage	V_{DF}		2.0		V	I _F = 150 A, V _{GS} = 0 V
Body to drain diode reverse recovery time	t _{rr}	_	140	_	ns	$I_F = 150 \text{ A}, V_{GS} = 0 \text{ V}$ di/dt = 100 A/ μ s

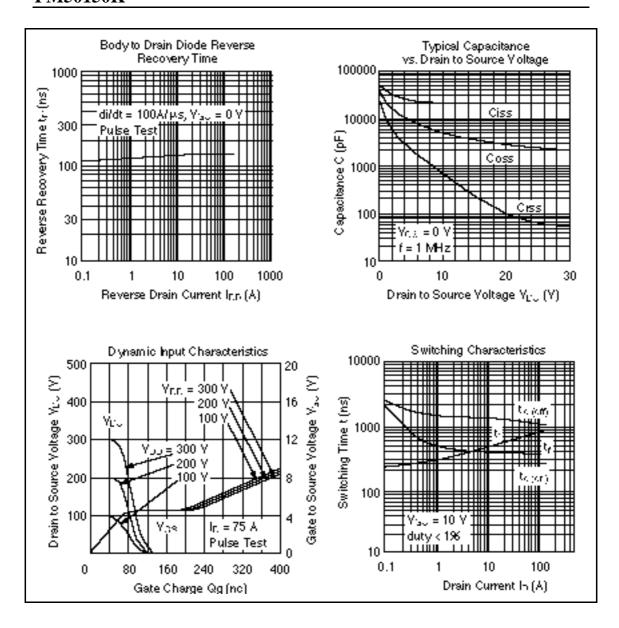
Note: 1. Pulse Test

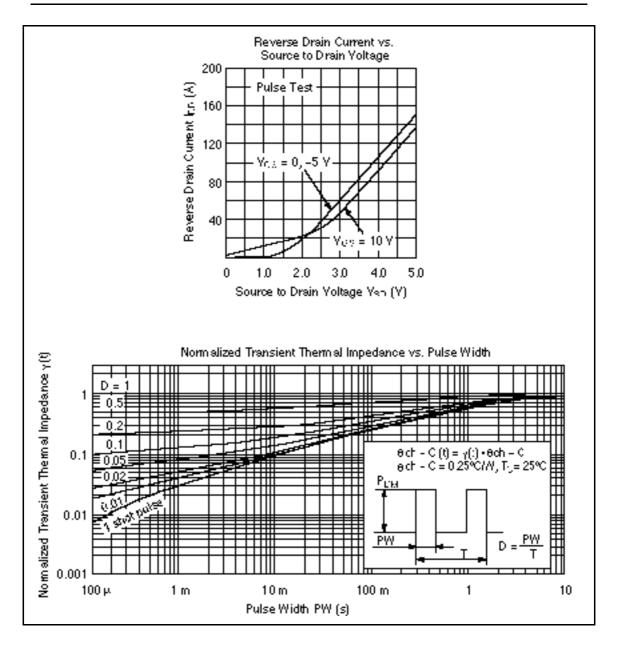
Mechanical Characteristics

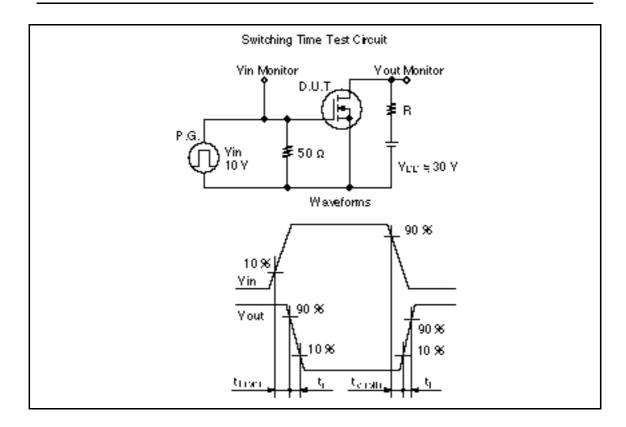
Item	Symbol	Condition	Rating	Unit
Fixing strength	_	Mounting into main-terminal with M4 screw	1.45 to 1.95	N-m
	_	Mounting into heat sink with M5 screw	1.95 to 2.9	N-m
Weight	_	Typical value	380	g





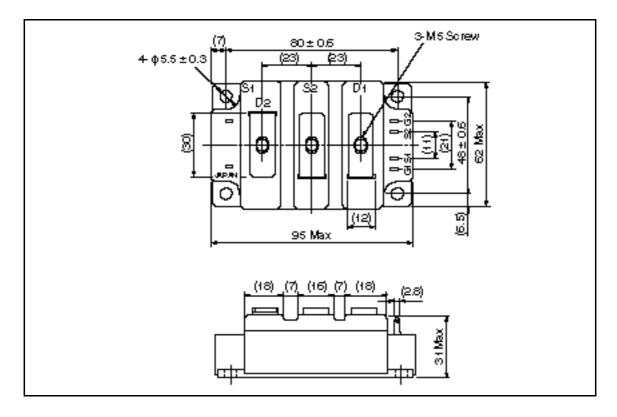






Package Dimensions

Unit: mm



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